Cu paste for MLCC outer electrode

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Grade number: TCU-101G

Features

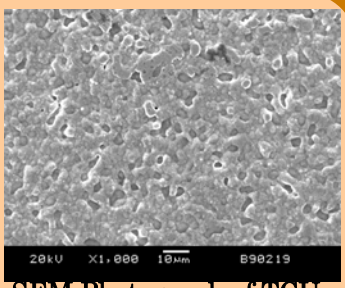
TCU-101G is developed for outer electrode of chip devices.(please ask about adaptive size.)
This builds up denser electrode to our former Cu paste, and materialize merits such as;

1. Good adhesion to base material.
2. Hardness of the electrode surface for good resistance against erosion and mechanical shock.

Characteristics

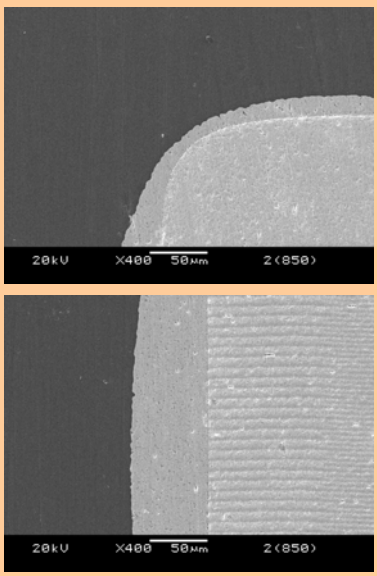
Item	Typical measurement value
Content	81±3wt%
Viscosity	42±5Pa·s
Solvent	Terpineol
Firing temperature	850℃

Appearance
1608 chip size

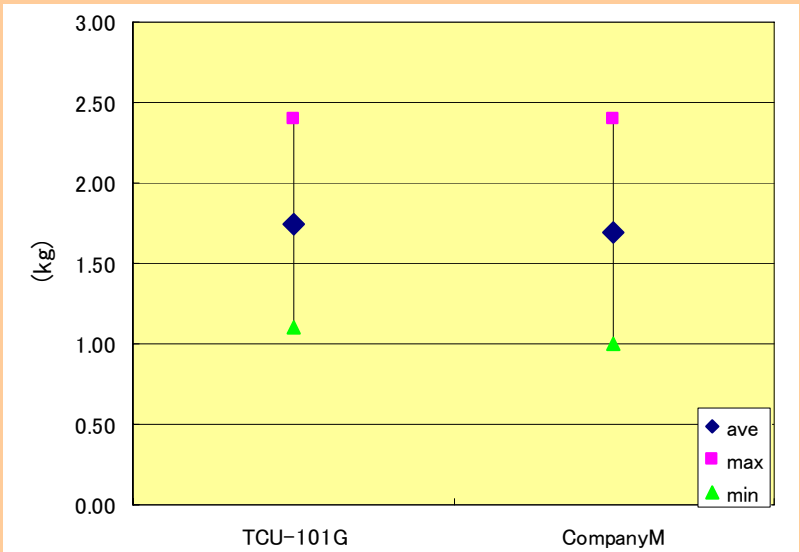


SEM Photograph of TCU-101G after sintering

Evaluation features



SEM Photographs of cross section



Tensile strength
1608 chip size

・It is demonstrated that TCU-101G attains stable tensile strength at out solder-mounted push and pull test thanks to the high-density.

＜Our tensile test process＞

1. Printing the paste on a chip and sintering 850℃×10min and create a electrode.
2. Soldering lead wire at the both ends of the electrode.
3. Fixing a wire and pulling the other wire horizontally with push and pull gouge. Observing the load as tensile strength at the time of abruption of electrode.

We are happy to undertake customization for customer`s requirements.